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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.		
09/605,293	06/28/2000	DAVID L. CHAPEK	MIO-0037-VA	5927		
75	90 02/07/2005	EXAM	EXAMINER			
KILLWORTH GOTTMAN HAGAN SCHAEFF L L P			RICHARDS	RICHARDS, N DREW		
ONE DAYTON CENTRE, SUITE 500 DAYTON, OH 45402-2023			ART UNIT	PAPER NUMBER		
,			2815			
			DATE MAILED: 02/07/2003	DATE MAILED: 02/07/2005		

Please find below and/or attached an Office communication concerning this application or proceeding.



Application No.	Applicant(s)		
09/605,293	CHAPEK, DAVID L.		
Examiner	Art Unit		
N. Drew Richards	2815		

Advisory Action	09/605,293	CHAPEK, DAVID L.				
Before the Filing of an Appeal Brief	Examiner	Art Unit				
	N. Drew Richards	2815				
The MAILING DATE of this communication appe	ears on the cover sheet with the c	correspondence add				
		•				
THE REPLY FILED 27 January 2005 FAILS TO PLACE THIS APPLICATION IN CONDITION FOR ALLOWANCE. It is implicated the property of the following replies: (1) an amendment, affidavit, or other evidence, which places the application in condition for allowance; (2) a Notice of Appeal (with appeal fee) in compliance with 37 CFR 41.31; or (3) a Request for Continued Examination (RCE) in compliance with 37 CFR 1.114. The reply must be filed within one of the following time periods:						
a) The period for reply expiresmonths from the mailing of the period for reply expires on: (1) the mailing date of this Adverse, however, will the statutory period for reply expire later the Examiner Note: If box 1 is checked, check either box (a) or (b) MONTHS OF THE FINAL REJECTION. See MPEP 706.07(f	isory Action, or (2) the date set forth in the an SIX MONTHS from the mailing date of ONLY CHECK BOX (b) WHEN THE FI	f the final rejection.				
Extensions of time may be obtained under 37 CFR 1.136(a). The date on which the petition under 37 CFR 1.136(a) and the appropriate extension fee have been filed is the date for purposes of determining the period of extension and the corresponding amount of the fee. The appropriate extension fee under 37 CFR 1.17(a) is calculated from: (1) the expiration date of the shortened statutory period for reply originally set in the final Office action; or (2) as set forth in (b) above, if checked. Any reply received by the Office later than three months after the mailing date of the final rejection, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b). NOTICE OF APPEAL						
2. The reply was filed after the date of filing a Notice of Appeal, but prior to the date of filing an appeal brief. The Notice of Appeal was filed on A brief in compliance with 37 CFR 41.37 must be filed within two months of the date of filing the Notice of Appeal (37 CFR 41.37(a)), or any extension thereof (37 CFR 41.37(e)), to avoid dismissal of the appeal. Since a Notice of Appeal has been filed, any reply must be filed within the time period set forth in 37 CFR 41.37(a). AMENDMENTS						
3. The proposed amendment(s) filed after a final rejection, (a) They raise new issues that would require further co (b) They raise the issue of new matter (see NOTE below (c) They are not deemed to place the application in below appeal; and/or (d) They present additional claims without canceling a NOTE: (See 37 CFR 1.116 and 41.33(a)). 	nsideration and/or search (see NO ow); tter form for appeal by materially re corresponding number of finally re	TE below); educing or simplifying				
4. The amendments are not in compliance with 37 CFR 1.15. Applicant's reply has overcome the following rejection(s	I21. See attached Notice of Non-Co):	•	,			
 Newly proposed or amended claim(s) would be a the non-allowable claim(s). For purposes of appeal, the proposed amendment(s): a) how the new or amended claims would be rejected is pro The status of the claim(s) is (or will be) as follows: Claim(s) allowed: Claim(s) objected to: 	will not be entered, or b) w	-	•			
Claim(s) rejected: <u>9-12 and 14.</u> Claim(s) withdrawn from consideration: AFFIDAVIT OR OTHER EVIDENCE						
The affidavit or other evidence filed after a final action, be because applicant failed to provide a showing of good an and was not earlier presented. See 37 CFR 1.116(e).	d sufficient reasons why the affida	vit or other evidence is	s necessary			
 The affidavit or other evidence filed after the date of filing entered because the affidavit or other evidence failed to one showing a good and sufficient reasons why it is necessar The affidavit or other evidence is entered. An explanation 	overcome <u>all</u> rejections under appea y and was not earlier presented. S	al and/or appellant fai see 37 CFR 41.33(d)(Is to provide a 1).			
REQUEST FOR RECONSIDERATION/OTHER	of the states of the claims after t	only is below of allac	neu.			
 The request for reconsideration has been considered bu See Continuation Sheet. 			nce because:			
12. Note the attached Information Disclosure Statement(s).	(PTO/SB/08 or PTO-1449) Paper (No(s)				
13.		ow Now	,			
	Surrent Color					

Continuation of 11. does NOT place the application in condition for allowance because: Applicant's arguments are not persuasive. Applicant has argued that there is no teaching or suggestion in Henley et al. that their technique is applicable to treat the surface of a silicon dioxided layer, nor is there any suggestion in Henley et al. that if applied to the surface of a silicon dioxide layer, their treatment would successfully result in a silicon dioxide layer which is free of metal contaminants as claimed. First, even though Henley et al. do not expressly teach that their technique could be applied to the surface of a silicon dioxide layer it would have been obvious to one of ordinary skill in the art that their technique could be so applied. It is known in the prior art that implantation processes such as PSII can be used to implant into silicon dioxide layers. As for implanting into the surface, one of ordinary skill in the art would recognize that it a process can implant below the surface, one would only need to reduce the implantation energy to implant into the surface. Thus, one of ordinary skill in the art would recognize that Henley et al. PSII process would reasonably be expected to work in the process of implanting hydrogen into the surface of the silicon dioxide layer. One of ordinary skill in the art, upon considering applicant's admitted prior art and Henley et al. together, would reasonably expect the silicon dioxide layer to be free of metal contaminants as claimed. The admitted prior art teaches the specific source of the metal contamination, i.e. the metal is a result of the implantation apparatus, and Henley et al. expressly teach that their method (PSII) sometimes produces less metal contamination. Thus, one would reasonably expect the same level of metal contamination to result when using the implantation process of Henley et al. in the method of treating silicon dioxide of the prior art as when using the PSII process of the claimed invention. For these reasons, Henley et al. one of ordinary skill in the art would reasonably expect success in achieving the claimed invention when Henley et al. is combined with the admitted prior art.